



# UT3NN10

*Power MOSFET*

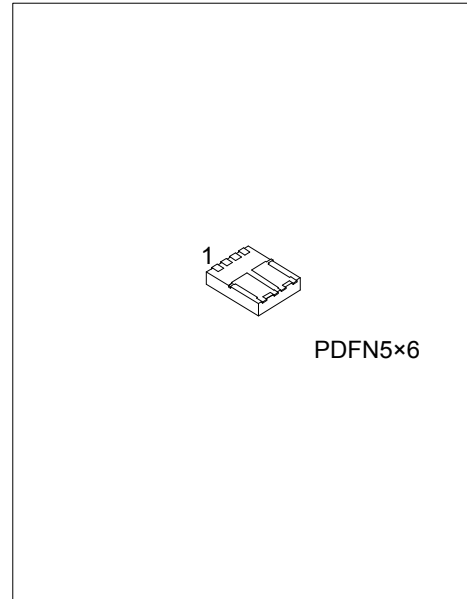
## 3.0A, 100V DUAL N-CHANNEL ENHANCEMENT MODE POWER MOSFET

■ DESCRIPTION

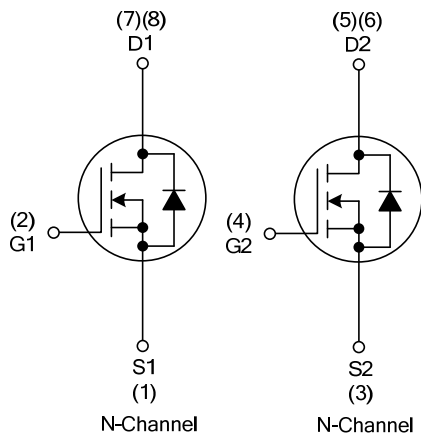
The UTC **UT3NN10** is a dual N-Channel enhancement mode power MOSFET, it provides designer with fast switching speed, ruggedized device design, low on-resistance and cost-effectiveness.

■ FEATURES

- \*  $R_{DS(ON)} \leq 0.15 \Omega @ V_{GS}=10V, I_D=3.0A$
- \*  $R_{DS(ON)} \leq 0.17 \Omega @ V_{GS}=4.5V, I_D=1.0A$
- \* Fast Switching Speed
- \* Simple Drive Requirement



■ SYMBOL



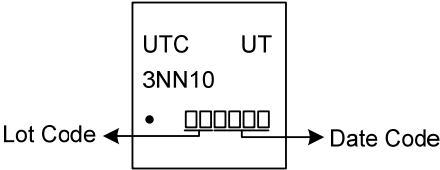
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment						Packing
Lead Free	Halogen Free		1	2	3	4	5, 6	7, 8	
UT3NN10L-P5060-R	UT3NN10G-P5060-R	PDFN5x6	S1	G1	S2	G2	D2	D1	Tape Reel

Note: Pin Assignment: S: Source G: Gate D: Drain

<p>UT3NN10G-P5060-R</p> <p>(1) Packing Type</p> <p>(2) Package Type</p> <p>(3) Green Package</p>	<p>(1) R: Tape Reel</p> <p>(2) P5060: PDFN5x6</p> <p>(3) G: Halogen Free and Lead Free, L: Lead Free</p>
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MARKING



■ ABSOLUTE MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current	Continuous(Note 3)	$I_D$	3
	Pulsed(Note 2)	$I_{DM}$	6
Avalanche Energy	Single Pulsed (Note 3)	$E_{AS}$	21
Peak Diode Recovery dv/dt (Note 4)	dv/dt	3	V/ns
Power Dissipation	$P_D$	3.6	W
Junction Temperature	$T_J$	+150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^{\circ}\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3.  $L = 0.1\text{mH}$ ,  $I_{AS} = 20.5\text{A}$ ,  $V_{DD} = 25\text{V}$ ,  $R_G = 25\ \Omega$  Starting  $T_J = 25^{\circ}\text{C}$

4.  $I_{SD} \leq 3.0\text{A}$ ,  $di/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^{\circ}\text{C}$

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	$\theta_{JA}$	35	$^{\circ}\text{C}/\text{W}$

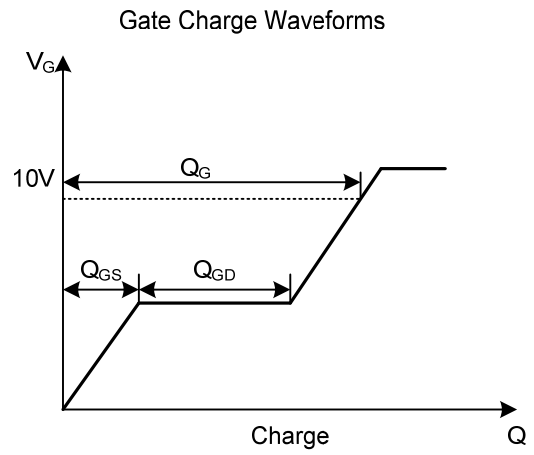
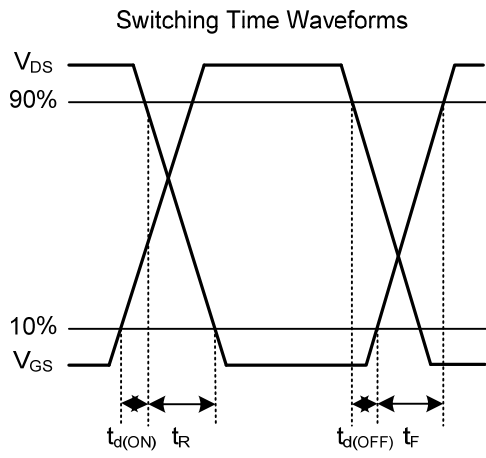
Note: Device mounted on FR-4 substrate  $P_c$  board, 2oz copper, with 1inch square copper plate.

■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, unless otherwise specified)

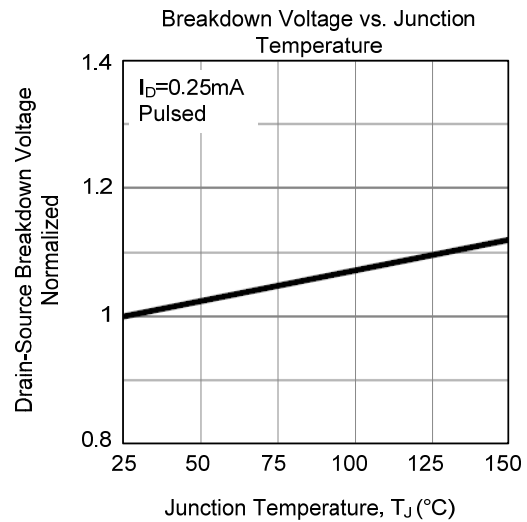
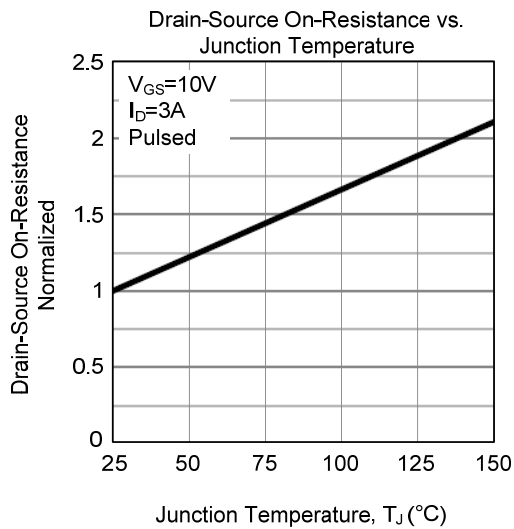
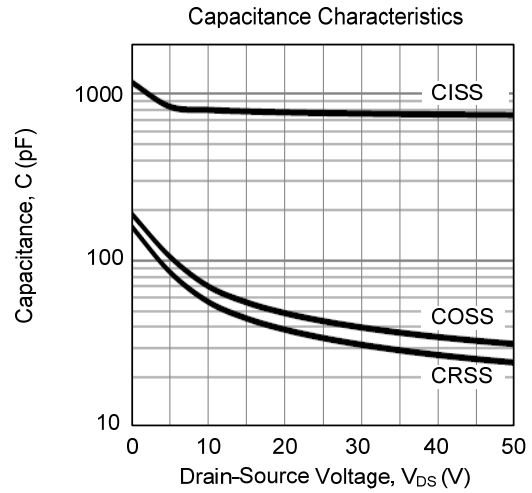
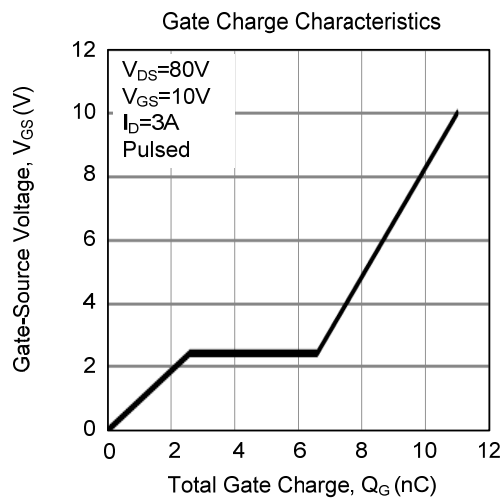
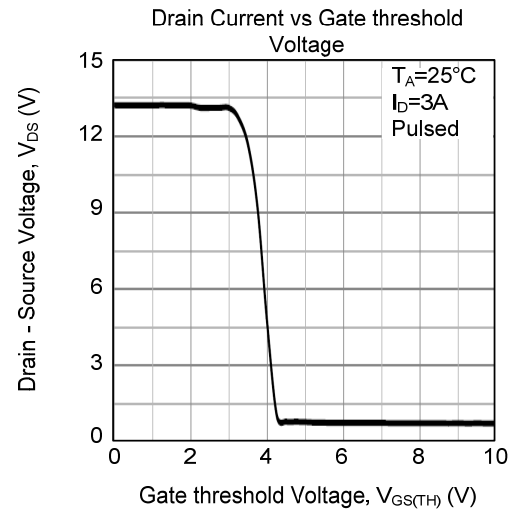
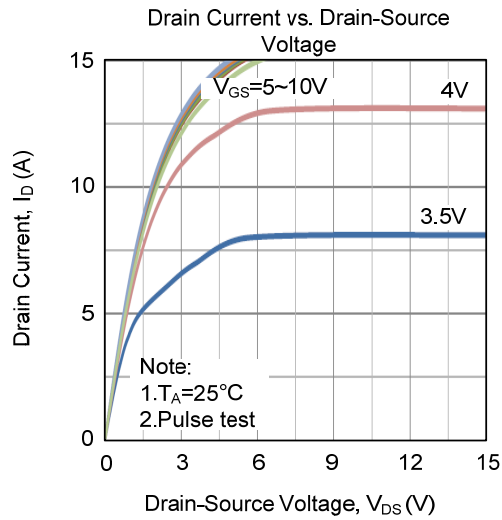
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>OFF CHARACTERISTICS</b>								
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100			V	
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μA	
Gate-Source Leakage Current	Forward	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =20V			100	nA	
	Reverse		V <sub>DS</sub> =0V, V <sub>GS</sub> =-20V			-100	nA	
<b>ON CHARACTERISTICS</b>								
Gate Threshold Voltage		V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0		3.0	V	
Drain-Source On-State Resistance (Note 1)		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.0A			0.15	Ω	
			V <sub>GS</sub> =4.5V, I <sub>D</sub> =1.0A			0.17	Ω	
<b>DYNAMIC PARAMETERS</b>								
Input Capacitance		C <sub>ISS</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz		730		pF	
Output Capacitance		C <sub>OSS</sub>				46		pF
Reverse Transfer Capacitance		C <sub>RSS</sub>				36		pF
<b>SWITCHING PARAMETERS</b>								
Total Gate Charge (Note 1)	10V	Q <sub>G</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =10V, I <sub>D</sub> =3.0A I <sub>G</sub> =1mA (Note 1, 2)		11		nC	
	4.5V				7.3		nC	
Gate-Source Charge		Q <sub>GS</sub>				2.6		nC
Gate-Drain Charge		Q <sub>GD</sub>				4		nC
Turn-ON Delay Time (Note 1)		t <sub>D(ON)</sub>				5.6		ns
Turn-ON Rise Time		t <sub>R</sub>		V <sub>DS</sub> =80V, V <sub>GS</sub> =10V, I <sub>D</sub> =3.0A, R <sub>G</sub> =25Ω (Note 1, 2)		16		ns
Turn-OFF Delay Time		t <sub>D(OFF)</sub>				85		ns
Turn-OFF Fall Time		t <sub>F</sub>				35		ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>								
Maximum Continuous Drain-Source Diode Forward Current		I <sub>S</sub>				3	A	
Maximum Pulsed Drain-Source Diode Forward Current		I <sub>SM</sub>				6	A	
Drain-Source Diode Forward Voltage (Note 1)		V <sub>SD</sub>	I <sub>S</sub> =1.2A, V <sub>GS</sub> =0V			1.2	V	
Body Diode Reverse Recovery Time (Note 1)		t <sub>rr</sub>	I <sub>S</sub> =3.0A, V <sub>GS</sub> =0V,		70		ns	
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>	di <sub>F</sub> /dt=100A/μs		87		nC	

Notes: 1. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%.  
 2. Essentially independent of operating temperature.

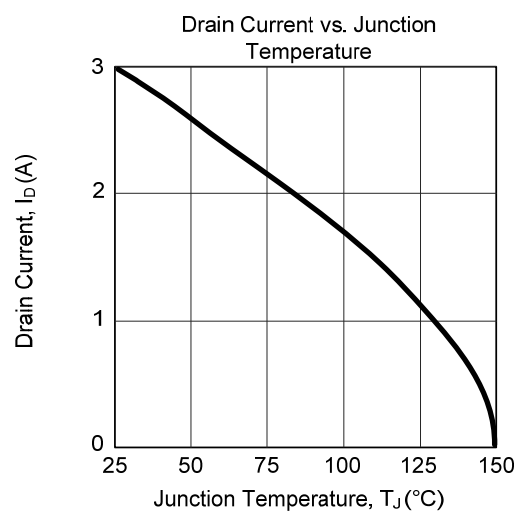
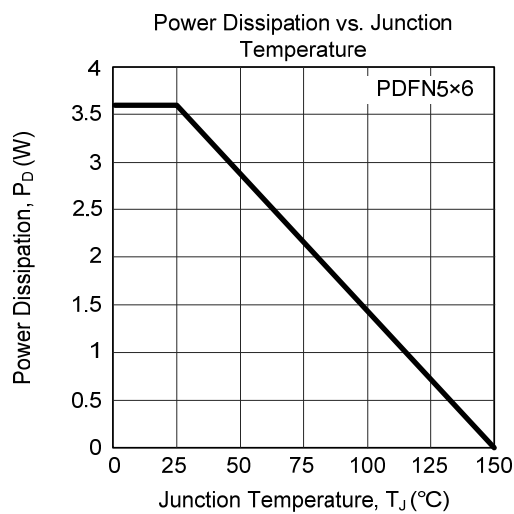
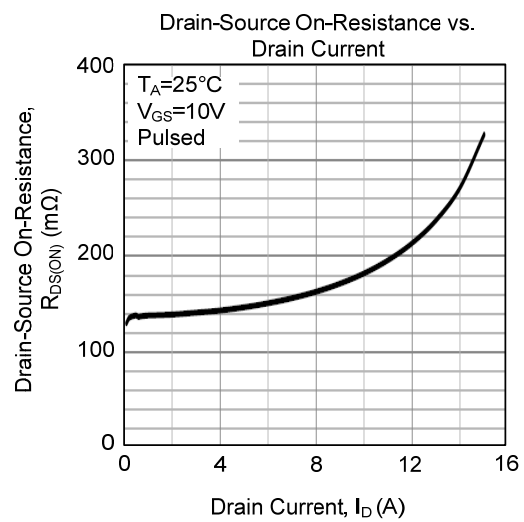
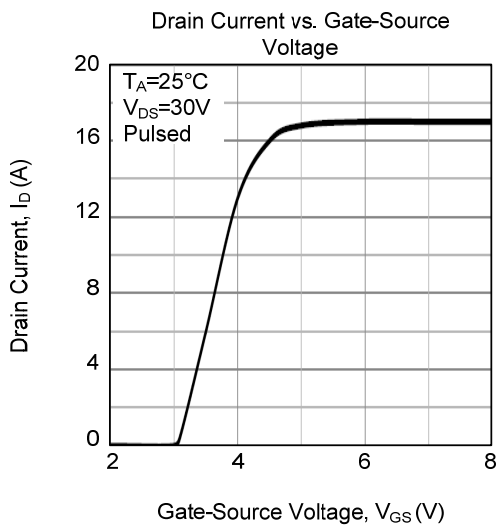
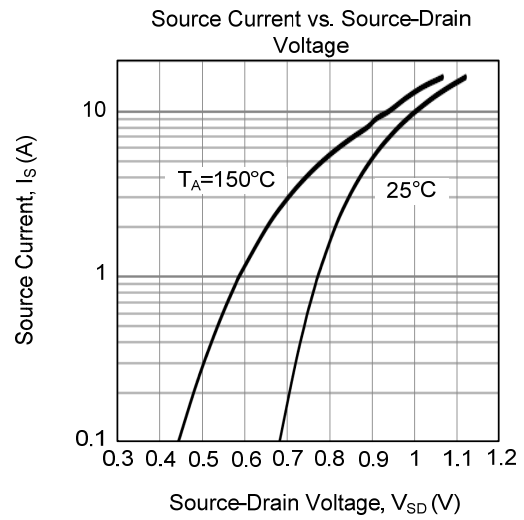
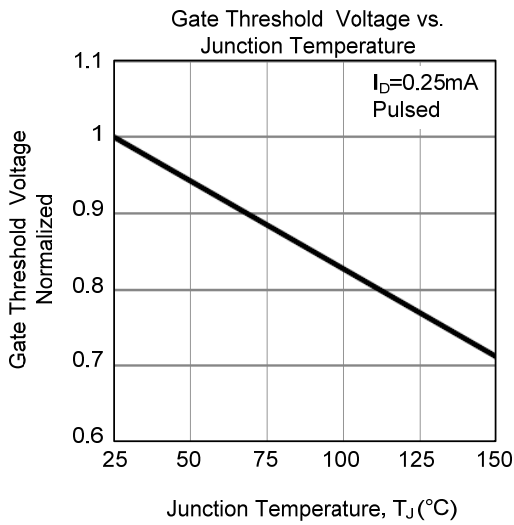
## ■ TEST CIRCUITS AND WAVEFORMS



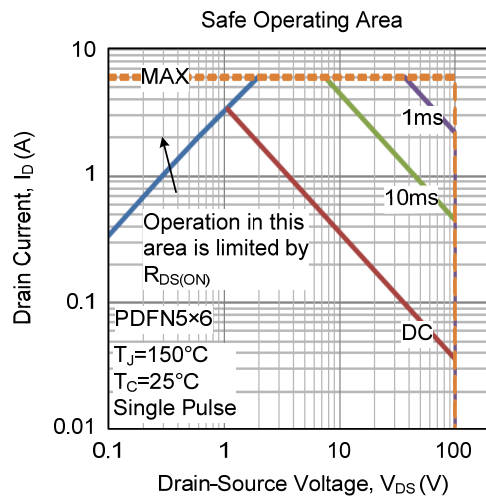
## TYPICAL CHARACTERISTICS



## ■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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